ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. Il international and Par	PC, Bannock	burn, Illinois. A	ll rights reserved un tions.	nder both	This docume level parts, t	ent is a decla the declaratio	ration of the s	substances es all lowe	within the manu r level materials	afacturer listed for which the	l item. N manufa	Note: if the acturer has	e item is an ass s engineering r	embly with lower esponsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information															
Company name* Co			Company unique ID			Unique ID Authority					Response Date*				
onsemi											2024-05-19				
Contact Name Title -			ïtle - Contact			Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title -			le - Representative			Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards	Product Envir	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective D	ate Version	ı 1	Manufacturing Site		Weigh	nt*	UOM	Unit Type	
	MC74H	C164ADTR2G	LOG CMOS SHIFT REG 8BIT			2024-05-19]	PH1		45.24		mg	Each	
Manufacturing Proccess Informa	ion							'							
Terminal Plating / Grid Array Ma	terial	Ferminal Base A	Alloy J	J-STD-020 MSL Ra		Peak Process B		Temperature Max Time at Peak		t Peak Temper	Temperature Number		of Reflow Cycl	es	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		l		260		С	30 seco		conds 3				
Comments															
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.44	mg		Epoxy resin	proprietary data		0.144	mg
			Supplier	Silver (Ag)	7440-22-4		1.152	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.144	mg
Lead Frame	22.54	mg	Supplier	Zinc (Zn)	7440-66-6		0.027	mg
			Supplier	Iron (Fe)	7439-89-6		0.5297	mg
			Supplier	Copper (Cu)	7440-50-8		21.9765	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0068	mg
Mold Compound-Black	19.0	mg		Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenolic Resin	Proprietary Data		0.38	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.475	mg
			Supplier	Carbon Black (C)	1333-86-4		0.095	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		17.1	mg
Plating	0.04	mg	Supplier	Palladium (Pd)	7440-05-3		0.003	mg
			В	Nickel (Ni)	7440-02-0		0.0364	mg
			Supplier	Gold (Au)	7440-57-5		0.0006	mg
Wire Bond - Cu	0.22	mg	Supplier	Copper (Cu)	7440-50-8		0.22	mg